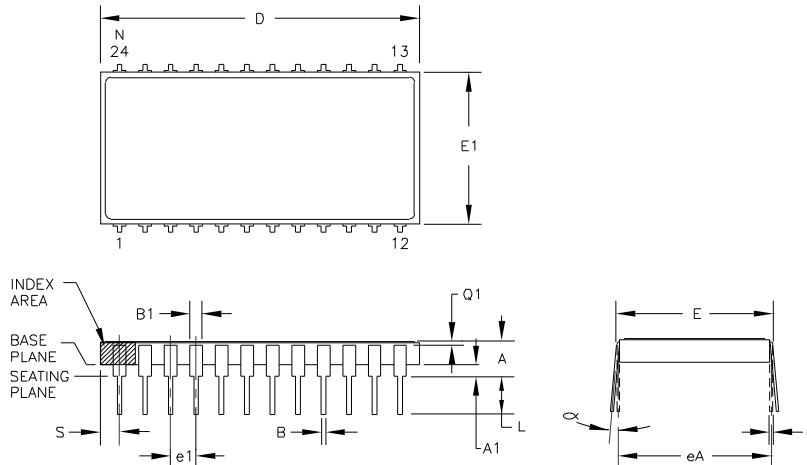


Package Number 176 - 24-Lead Side Braze DIP, .600 Wide



DIM	INCHES		MILLIMETERS		N O E	DIM	INCHES		MILLIMETERS		N O E
	MIN.	MAX.	MIN.	MAX.			MIN.	MAX.	MIN.	MAX.	
A	.085	.190	2.16	4.83		α	0°	15°	0°	15°	3
A1	.020	.070	0.51	1.78							
B	.015	.023	0.38	0.58	5						
B1	.038	.060	0.97	1.52	5						
C	.008	.012	0.20	0.30							
D	1.238	1.262	31.45	32.05							
E	.595	.625	15.11	15.88							
E1	.580	.610	14.73	15.49	6						
e1	.100 TYP.		2.54 TYP.		2						
eA	.600 TYP.		15.24 TYP.		2						
L	.125	.175	3.18	4.45							
N	24		24		4						
Q1	.010	--	0.25	--							
S	.060	.090	1.52	2.29							

NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5-1973.
2. LEADS WITHIN .005 IN. (0.13mm) RADIUS OF TRUE POSITION (TP) AT GAUGE PLANE WITH MAXIMUM MATERIAL CONDITION AND UNIT INSTALLED.
3. α APPLIES TO SPREAD LEADS PRIOR TO INSTALLATION.
4. N IS THE NUMBER OF TERMINAL POSITIONS.

5. OUTLINES ON WHICH THE SEATING PLANE IS COINCIDENT WITH THE PLANE (A1 = 0), TERMINALS LEAD STANDOFFS ARE NOT REQUIRED, AND B1 MAY EQUAL B ALONG ANY PART OF THE LEAD ABOVE THE SEATING/BASE PLANE.
6. E1 DOES NOT INCLUDE PARTICLES OF PACKING MATERIALS.
7. CONTROLLING DIMENSION: INCH.
8. A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN THE CROSS-HATCHED AREA.

PACKAGE NUMBER: ZZ176 | REV.: D
 JEDEC NUMBER: MO-038-AA
 WITH THE EXCEPTION OF DIM. D, S.



PACKAGE DRAWING

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